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Serial No. 10/502,506

AUG 08 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Eric Stephen Carlsgaard
Application No.: 10/502,506
Filed: July 23, 2004
Title: Flip Chip Die Bond Pads, Die Bond Pad Placement and Routing Optimization
Examiner: Huynh, Andy
Art Unit: 2818
Customer No.: 24498

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated June 6, 2006, for which a shortened statutory period of three months for response ending September 6, 2006, the following amendments and comments are submitted and reconsideration of the claim rejections is respectfully requested.

The Applicants submit that in view of the attached Certificate of Mailing, this response is timely.

Listing of the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being transmitted via facsimile to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 2313-1450 on August 8, 2006 at facsimile number (571) 273-8300.


Tracey Campbell